

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8401364

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GUOYUN GUAN	06/22/2023
MIN MENG	06/22/2023
JUN HU	06/22/2023
ZAIPING NIE	06/22/2023
RECEIVING PARTY DATA	
Name:	UNIVERSITY OF ELECTRONIC SCIENCE AND TECHNOLOGY OF CHINA
Street Address:	NO. 2006, XIYUAN AVE., WEST HI-TECH ZONE
Internal Address:	SICHUAN
City:	CHENGDU
State/Country:	CHINA
Postal Code:	611731
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17851348
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	15599993656
Email:	drewfortney@lawoffadf.com
Correspondent Name:	CENTRAL CALIFORNIA IP GROUP, P.C.
Address Line 1:	801 VILLAGE GREEN LN.
Address Line 2:	CENTRAL CALIFORNIA IP GROUP, P.C.
Address Line 4:	OKATIE, SOUTH CAROLINA 29909
ATTORNEY DOCKET NUMBER:	UESTC-004
NAME OF SUBMITTER:	ANDREW D. FORTNEY, PH.D., REG. NO. 34600
SIGNATURE:	/Andrew D. Fortney/
DATE SIGNED:	01/25/2024
Total Attachments: 2	

source=UESTC-004 Assignment#page1.tif

source=UESTC-004 Assignment#page2.tif

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

GUAN, Guoyun

MENG, Min

HU, Jun

NIE, Zaiping

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

**COMMON MODE REJECTION METHOD AND APPARATUS FOR
ELECTROMAGNETIC INDUCTION LOGGING**

Do hereby sell, assign and transfer to University of Electronic Science and Technology of China, a university of the People's Republic of China, having a place of business at No. 2006, Xiyuan Ave., West Hi-Tech Zone, Chengdu, Sichuan 611731, P.R. China,

its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that University of Electronic Science and Technology of China, hereinafter referred to as Assignee, may apply for and receive said Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this Assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Sole/First Inventor: GUAN, Guoyun	
Inventor's Signature: <i>Guan Guoyun</i>	Date: Month/Day/Year <i>6/22/2022</i>

Full Name of Second Inventor, if any: MENG, Min	
Inventor's Signature: <i>Meng Min</i>	Date: Month/Day/Year <i>6/22/2022</i>

Full Name of Third Inventor, if any: HU, Jun	
Inventor's Signature: <i>Hu Jun</i>	Date: Month/Day/Year <i>6/22/2022</i>

Full Name of Fourth Inventor, if any: NIE, Zaiping	
Inventor's Signature: <i>Nie Zaiping</i>	Date: Month/Day/Year <i>6/22/2022</i>

Full Name of Fifth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Sixth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Seventh Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Eighth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Ninth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year